

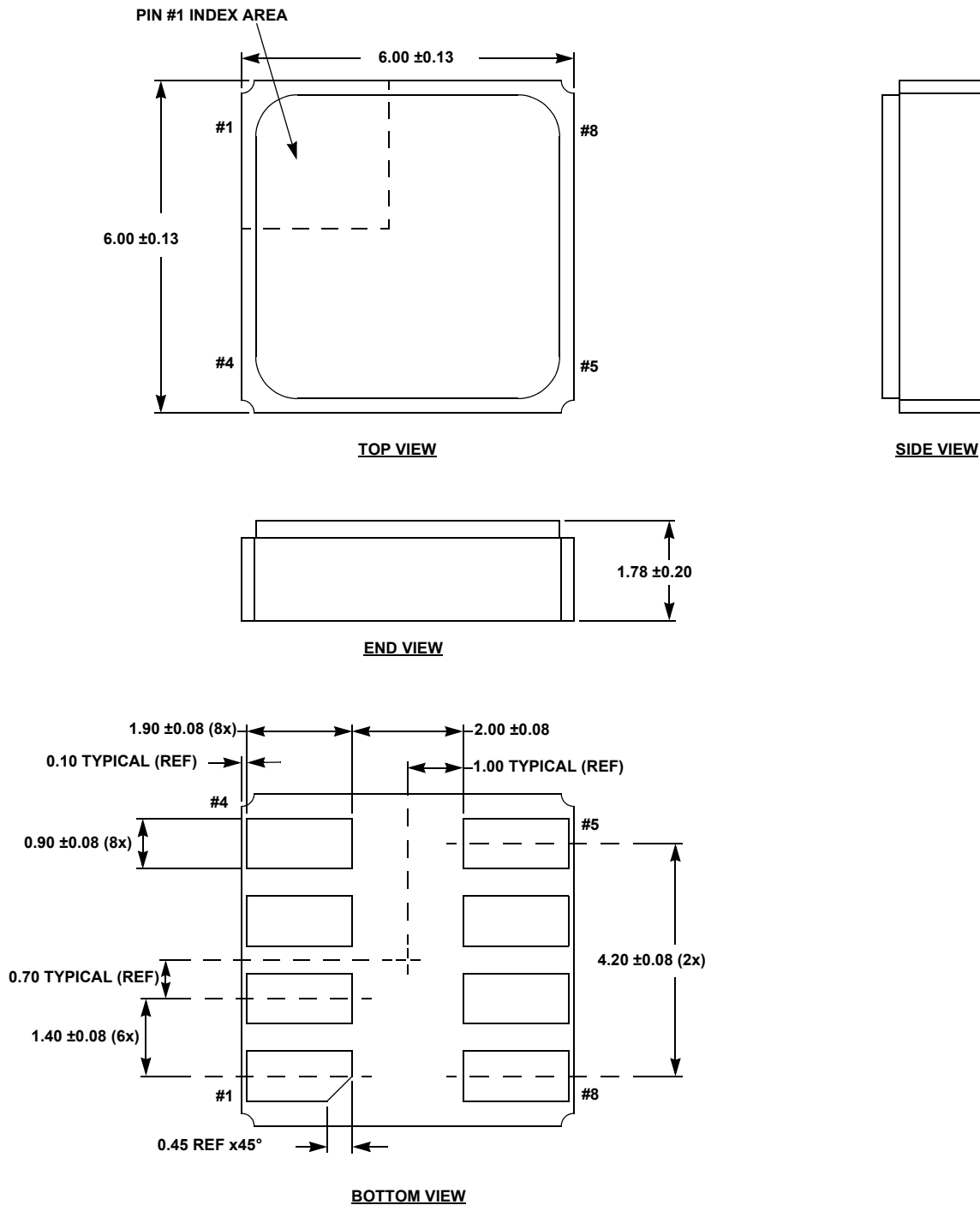
Hermetic Packages for Integrated Circuits

Package Outline Drawing

J8.A

8 PIN 6mmx6mm HERMETIC SURFACE MOUNT PACKAGE

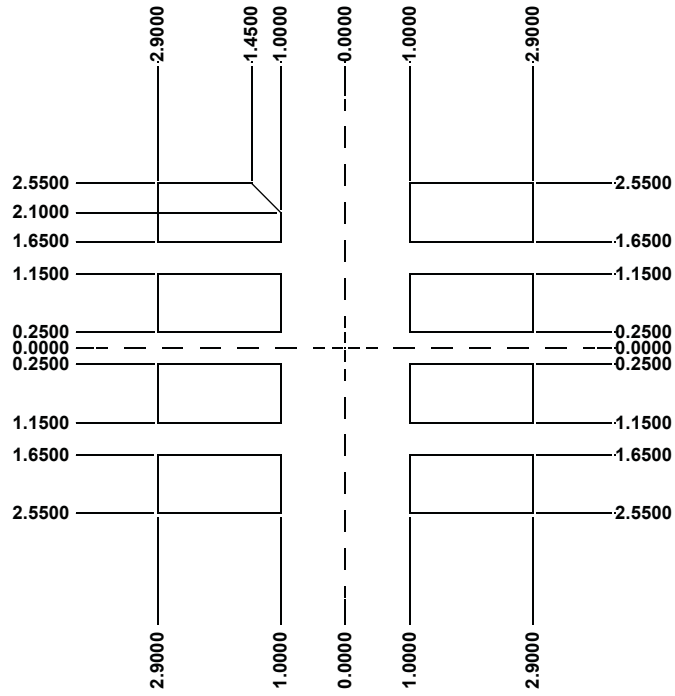
Rev 0, 3/16



NOTES:

1. The corner shape (radius, chamfer, etc.) may vary at the manufacturer's option from that shown on the drawing.
2. The package thickness dimension is the package height before being solder dipped.
3. Dimensions are in millimeters.

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TYPICAL RECOMMENDED LAND PATTERN